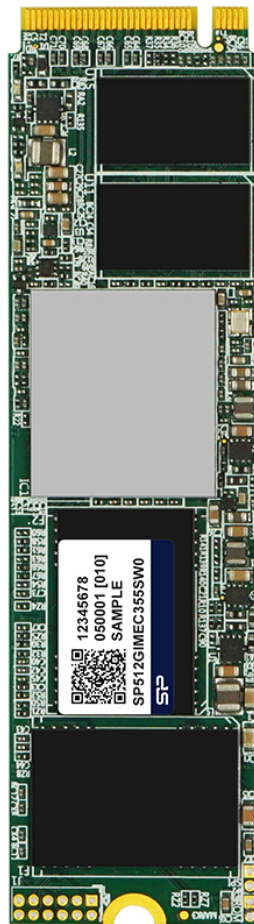


NGFF M.2 (B+M Key) standard form factor

 silicon-power.com/web/gb/product-MEC350S



Specifications

- Capacity
 - 128GB ~ 2TB
- Interface
 - PCIe Gen3x4, NVMe
- Storage Temperature
 - -55°C ~ 95°C
- Seq. Performance Read (max.)
 - 3,400 MB/s

- Seq. Performance Write (max.)
- 2,900 MB/s

- Random 4K Read (IOPS max.)
- 345000

- Random 4K Write (IOPS max.)
- 350000

- Power Requirement
- DC 3.3V

- Power Consumption(max.)
- 2450 mA

- Power Consumption (idle)
- 230 mA

- Dimension (mm)
- 80.0 x 22.0 x 3.6

- MTBF (est)
- ≧2,000,000 hrs

- Operating Temp. (Standard)
- SP***GIMEC35*SVo

- Operating Temp. (Wide)
- SP***GIMEC351SWo

- Operating Humidity
- 10% ~ 95% (30°C Max. Wet Bulb Temp)

- Vibration
- 15G, 10~2000Hz

- Drop
- 75cm

- Shock
- 1,500G@0.5ms

- Power Shield
- ●

- End-to-End Data Protection
- ●

- TRIM

- •
- S.M.A.R.T.
- •
- DEVSLP
- •
- AES 256
- •
- SP SMART Utility
- •
- External DRAM Buffer
- •
- Warranty
- 3 years and within TBW

Features

- NGFF M.2 (B+M Key) standard form factor
- Compliant with Serial ATA Revision 3.1 standard with 6.0 Gb/s transfer rate
- Equipped with advanced PFP technology (optional)
- Supports Data Security AES Encryption (optional)
- Support SP Toolbox SMART health monitoring software

MEC350S 3D TLC

Form Factor	NAND	Interface	Capacity	Temp.	P/N
M.2 2280	3D TLC	PCIe3.0	128GB	0~70°C	SP128GIMEC355SV0
M.2 2280	3D TLC	PCIe3.0	128GB	-40~85°C	SP128GIMEC351SW0
M.2 2280	3D TLC	PCIe3.0	256GB	0~70°C	SP256GIMEC355SV0
M.2 2280	3D TLC	PCIe3.0	256GB	-40~85°C	SP256GIMEC351SW0
M.2 2280	3D TLC	PCIe3.0	512GB	0~70°C	SP512GIMEC355SV0
M.2 2280	3D TLC	PCIe3.0	512GB	-40~85°C	SP512GIMEC351SW0
M.2 2280	3D TLC	PCIe3.0	1TB	0~70°C	SP010TIMEC355SV0
M.2 2280	3D TLC	PCIe3.0	2TB	0~70°C	SP020TIMEC352SV0

